

FEATURES

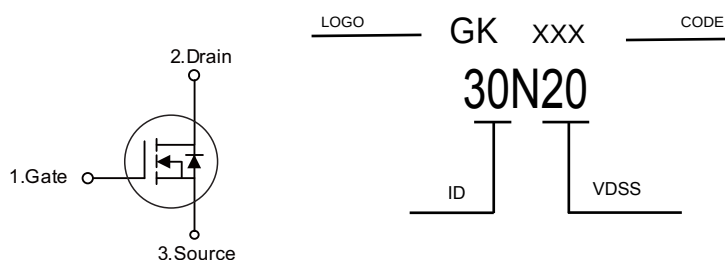
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS Tested
- 100% ΔV_{DS} Tested
- Halogen-free; RoHS-compliant

DESCRIPTION

- Load Switch
- PWM Application
- Power Management

V_{DS} 200V
 I_D 30 A
 $R_{DS(ON)}$ 82m Ω

GK XXX
30N20



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-to-Source Voltage	200	V
V_{GS}	Gate-to-Source Voltage	± 30	V
I_D	Continuous Drain Current	$T_C = 25^\circ\text{C}$	A
		$T_C = 100^\circ\text{C}$	
I_{DM}	Pulsed Drain Current ⁽¹⁾	Refer to Fig.4	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	551	mJ
P_D	Power Dissipation	$T_C = 25^\circ\text{C}$	W
		$T_C = 100^\circ\text{C}$	
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽³⁾	61	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.6	

Electrical characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	200	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =200V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±30V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	2.0	3.0	4.0	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽⁴⁾	V _{GS} = 10V, I _D =10A	-	82	120	mΩ
Dynamic Characteristics						
R _g	Gate Resistance	f = 1MHz	-	2.6	-	Ω
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 100V, f = 1MHz		1569		pF
C _{oss}	Output Capacitance			126		pF
C _{rss}	Reverse Transfer Capacitance			21		pF
Q _g	Total Gate Charge	V _{GS} = 0 to 10V V _{DS} = 100V, I _D = 28A	25	35	48	nC
Q _{gs}	Gate Source Charge		8	11	14	nC
Q _{gd}	Gate Drain("Miller") Charge		10	14	18	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} = 10V, V _{DD} = 100V I _D = 28A, R _{GEN} = 24Ω	-	21	-	ns
t _r	Turn-On Rise Time		-	76	-	ns
t _{d(off)}	Turn-Off DelayTime		-	77	-	ns
t _f	Turn-Off Fall Time		-	60	-	ns
Body Diode Characteristics						
I _S	Maximum Continuous Body Diode Forward Current		-	-	28	A
I _{SM}	Maximum Pulsed Body Diode Forward Current		-	-	112	A
V _{SD}	Body Diode Forward Voltage	V _{GS} = 0V, I _S = 26A	-		1.2	V
trr	Body Diode Reverse Recovery Time	I _F = 28A, di/dt = 100A/us	122	171	232	ns
Qrr	Body Diode Reverse Recovery Charge		-	1123	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting $T_J=25^\circ\text{C}$, $V_{DD}=50\text{V}$, $V_G=10\text{V}$, $R_G=25\text{ohm}$, $L=10\text{mH}$, $I_{AS}=10.5\text{A}$, $V_{DD}=0\text{V}$ during time in avalanche.
 3. $R_{\theta JA}$ is measured with the device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square pad layout.
 4. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

RATING AND CHARACTERISTIC CURVES

Figure 1: Power De-rating

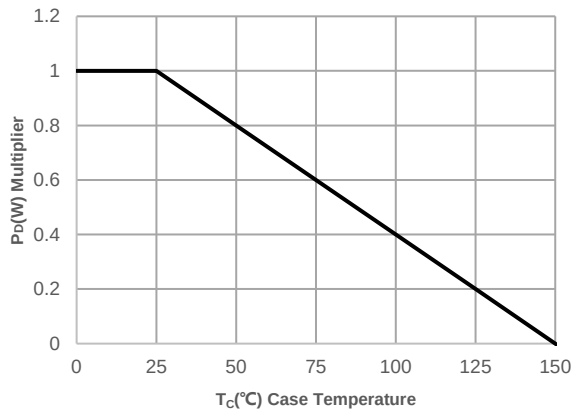


Figure 2: Current De-rating

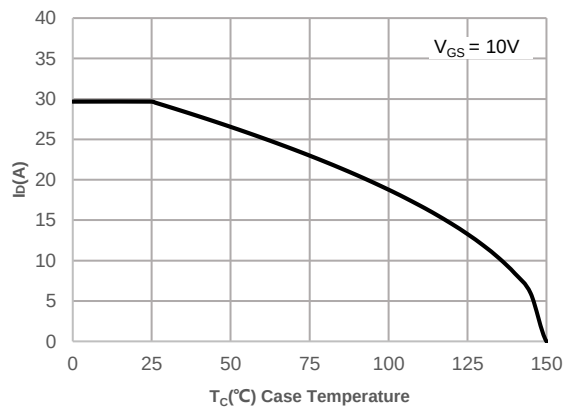


Figure 3: Normalized Maximum Transient Thermal Impedance

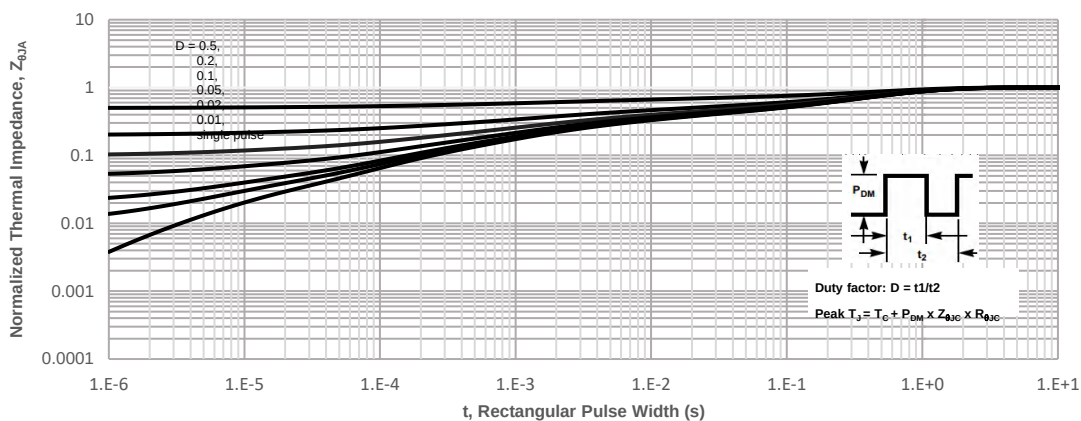
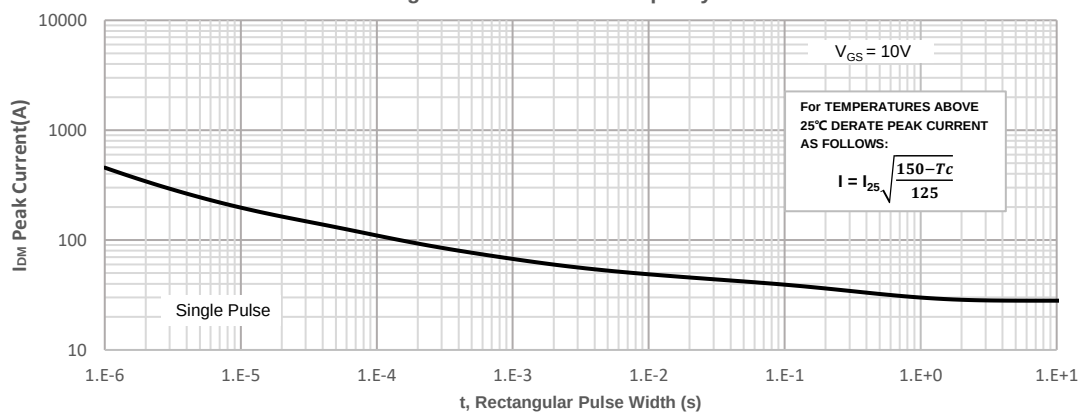


Figure 4: Peak Current Capacity



RATING AND CHARACTERISTIC CURVES

Figure 5: Output Characteristics

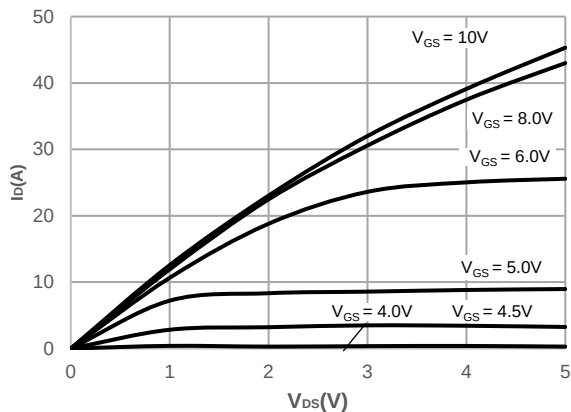


Figure 6: Typical Transfer Characteristics

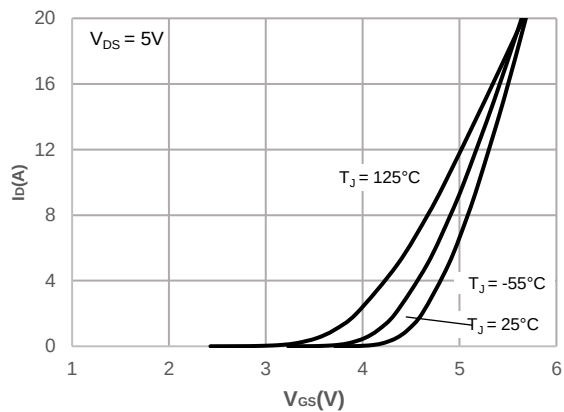


Figure 7: On-resistance vs. Drain Current

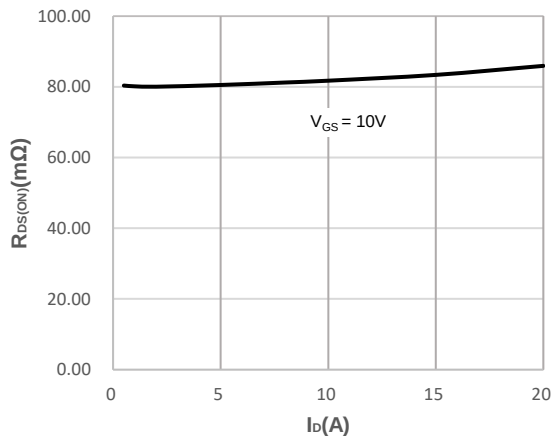


Figure 8: Body Diode Characteristics

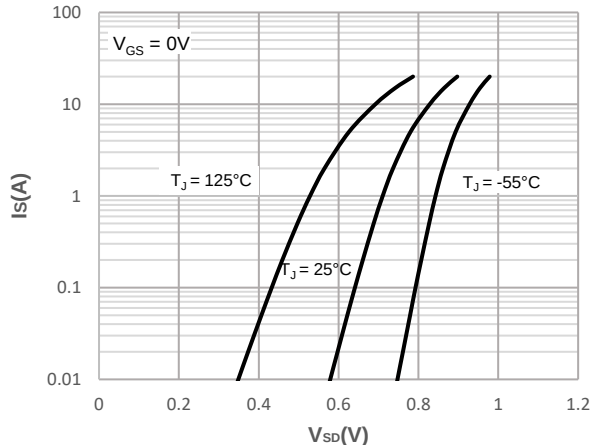


Figure 9: Gate Charge Characteristics

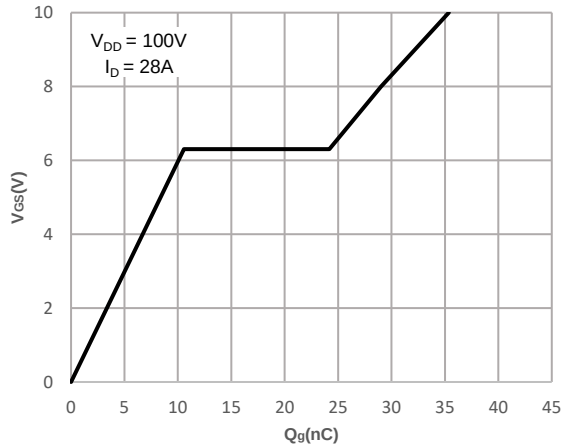
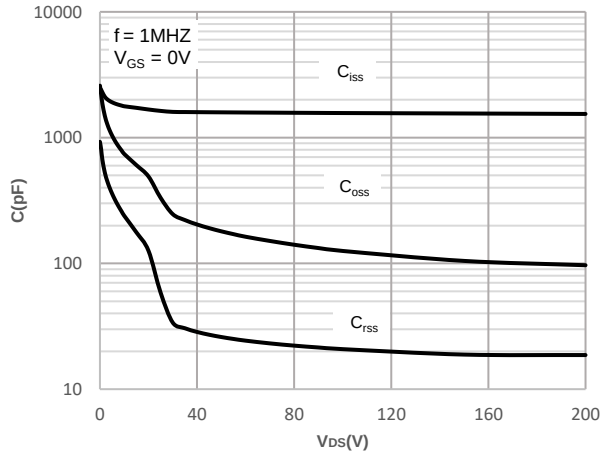


Figure 10: Capacitance Characteristics



RATING AND CHARACTERISTIC CURVES

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

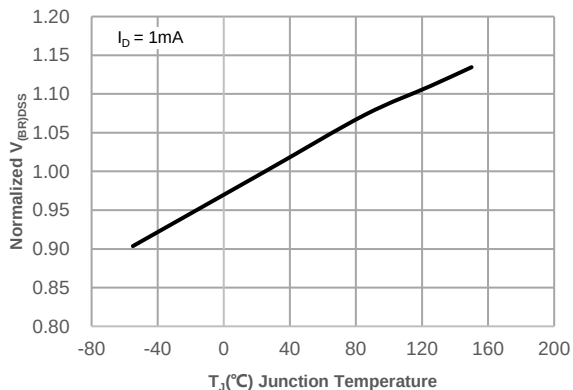


Figure 12: Normalized on Resistance vs. Junction Temperature

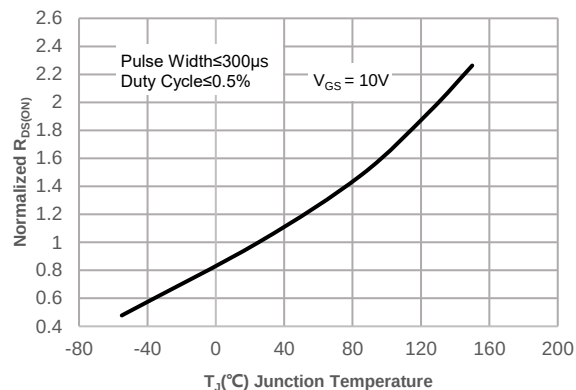


Figure 13: Normalized Threshold Voltage vs. Junction Temperature

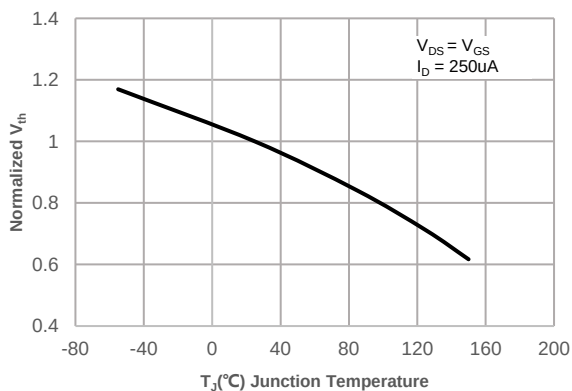


Figure 14: $R_{DS(on)}$ vs. V_{GS}

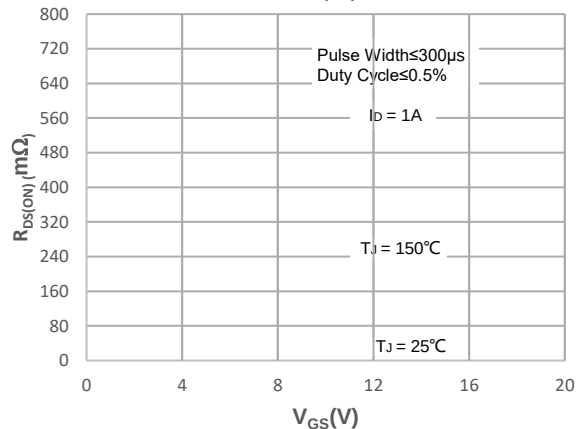
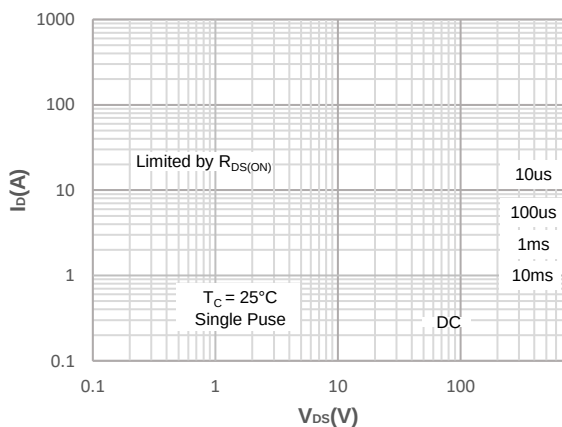


Figure 15: Maximum Safe Operating Area



TEST CIRCUIT

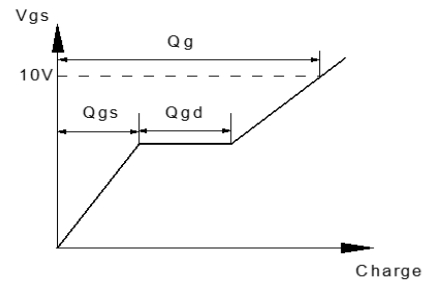
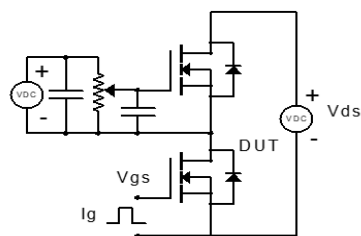


Figure 1: Gate Charge Test Circuit & Waveform

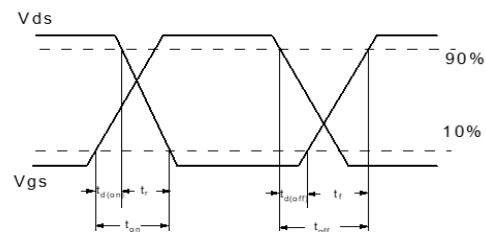
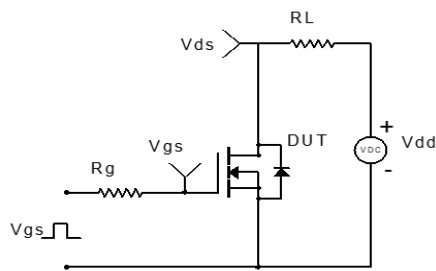


Figure 2: Resistive Switching Test Circuit & Waveform

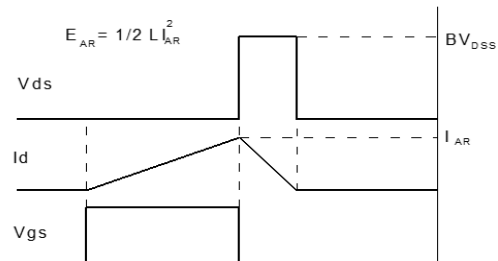
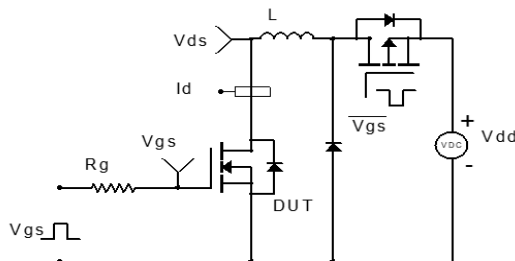


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

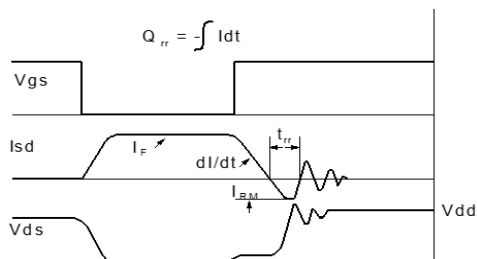
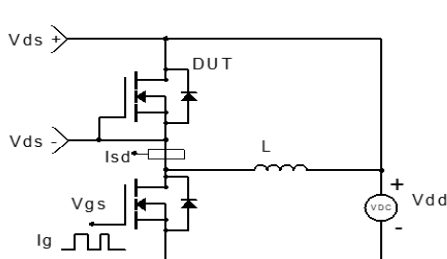
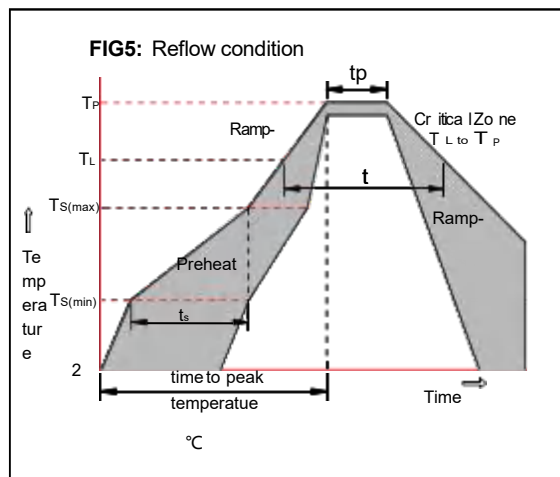


Figure 4: Diode Recovery Test Circuit & Waveform

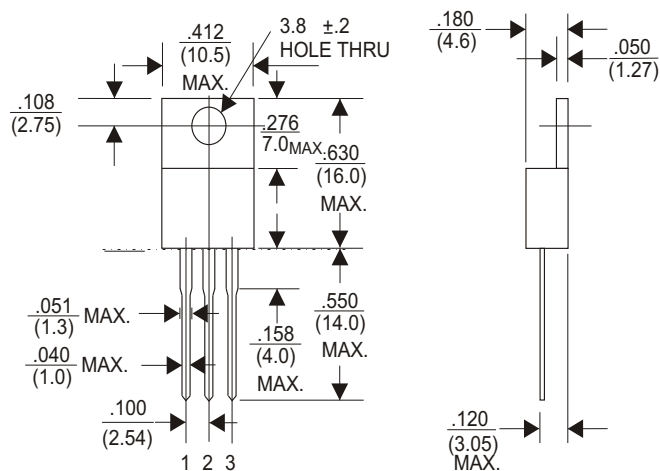
Soldering parameters

Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



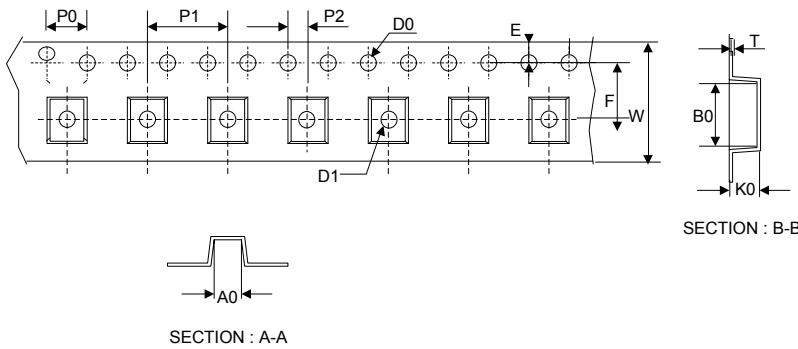
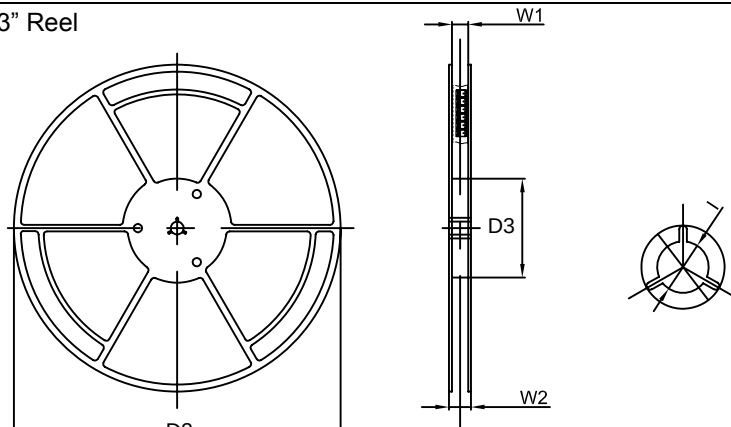
Package Dimensions & Suggested Pad Layout

TO-220



Dimensions in inches and (millimeters)

Tape & reel specification

Tape		Symbol	Dimension (mm)
 SECTION : A-A SECTION : B-B		P0	4.00±0.20
		P1	8.00±0.20
		P2	2.00±0.20
		D0	1.55±0.15
		D1	1.55±0.20
		E	1.75±0.20
		F	7.50±0.20
		W	16.00±0.20
		A0	7.10±0.20
		B0	10.50±0.20
		K0	2.70±0.20
		T	0.30±0.10
		D2	330.0±5.0
		D3	100.0±4.0
		W1	20.0±5.0
13" Reel		W2	25.0±5.0
		I	13.0±2.0
		Quantity: 2500PCS	